Slurry for Polishing a Surface Comprising a Ligand or Chelating Agent

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ABSTRACT

A novel slurry for polishing and a method of polishing using a slurry is disclosed. The slurry may include a colloidal silica abrasive in an aqueous solution. The slurry further includes a chelating agent that is believed to remove adsorbed ions from the surface of the layer being polished. The method may be used to polish a surface comprising, for example nickel and the chelating agent may be, for example, ammonium oxalate.

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